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02/25/02

PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10084787	FILING DATE 02/25/2002	CLASS 257	SUBCLASS 778	GAU 2811	EXAMINER Williams
**APPLICANTS: Pendse Rajendra; Tam Samuel;					
**CONTINUING DATA VERIFIED: THIS APPLN CLAIMS BENEFIT OF 60/272,236 02/27/2001					
** FOREIGN APPLICATIONS VERIFIED:					
PG-PUB DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO			
35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		CPAC 1010-2 US			
Verified and Acknowledged Examiners's initials					
TITLE : Super-thin high speed flip chip package					
U.S. DEPT. OF COMM /PAT. & TM-PTO-436L (Rev. 12-94)					

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NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg.
		Print Fig.	
<input type="checkbox"/> TERMINAL DISCLAIMER		Primary Examiner	
		Application Examiner	
		PREPARED FOR ISSUE	
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